

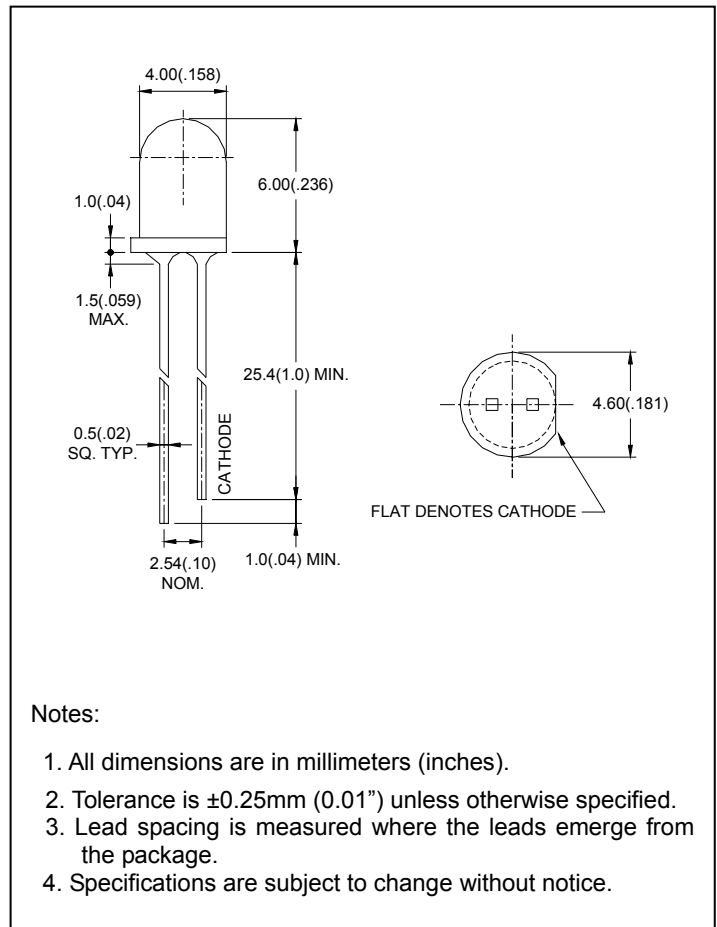
● Features:

1. Chip material: GaAsP/GaP
2. Emitted color : Hi-Eff Red
3. Lens Appearance : Red Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 4mm diameter package
9. This product don't contained restriction substance, compliance ROHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions:



● Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_d	80	mW
Forward Current	I_F	30	mA
Peak Forward Current* ¹	I_{FP}	150	mA
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	$-40^\circ\text{C} \sim 80^\circ\text{C}$	
Storage Temperature	T_{stg}	$-40^\circ\text{C} \sim 85^\circ\text{C}$	
Soldering Temperature	T_{sol}	260°C (for 5 seconds)	

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	I _F =20mA	-	2.0	2.6	V
Luminous Intensity	I _v	I _F =20mA	-	70	-	mcd
Reverse Current	I _R	V _R =5V	-	-	100	μA
Peak Wave Length	λ _p	I _F =20mA	-	640	-	nm
Dominant Wave Length	λ _d	I _F =20mA	617	-	638	nm
Spectral Line Half-width	Δλ	I _F =20mA	-	40	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	-	55	-	deg

● Typical Electro-Optical Characteristics Curves

Fig.1 Relative intensity vs. Wavelength

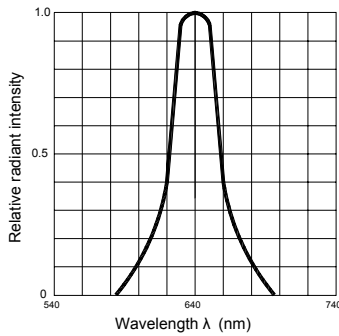


Fig.2 Forward current derating curve vs. Ambient temperature

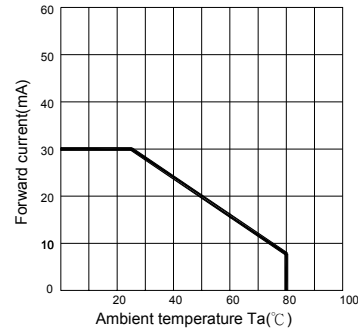


Fig.3 Forward current vs. Forward voltage

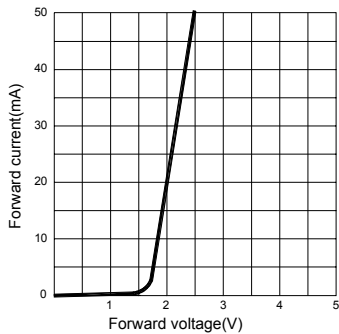


Fig.4 Relative luminous intensity vs. Ambient temperature

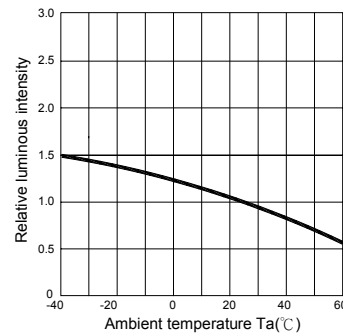


Fig.5 Relative luminous intensity vs. Forward current

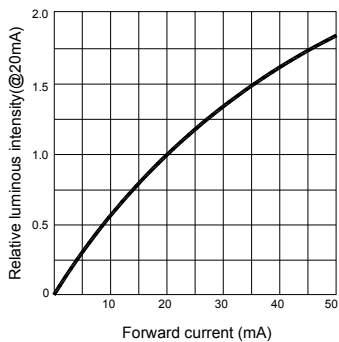


Fig.6 Radiation diagram

